Amendments to the Claims

Please cancel claims 13 and 15 without prejudice.

The following listing of claims will replace all prior versions and/or listings of claims in the application:

Listing of Claims:

1. (Currently amended): A process for producing a printed wiring board, which comprises: gluing a prepreg to a metal foil surface and hot pressing the ~~prepeg~~ prepreg and the metal foil surface to produce a laminate board, and forming a circuit on an outer layer of the laminate board to yield a printed wiring board; wherein said prepreg is manufactured by impregnating a reinforcing material with an epoxy resin composition followed by drying and semi-curing the composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator and a silica filler; wherein said silica filler is a silica filler which has a shape having at least two planes, and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

2. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is a silica filler having at least two planes in the shape, an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 10 m^2/g and 20 m^2/g.

3. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is added in an amount of from 3% to 80% by weight per the solid content of the resin.

4. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is a silica filler having an electric conductivity of 15 μs or less.

5. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is a silica filler which has been vitrified through melting at a temperature of 1800°C or higher.

6. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin is an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin obtained by reacting a dihydric phenol with a bisphenol A type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

7. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin is an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin possessing a dicyclopentadienyl structure in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

8. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin is an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing of a novolac type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

9. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin composition is a bromine-free epoxy resin composition.

10. (Previously presented): A process for producing a printed wiring board, which comprises: coupling a prepreg to a metal foil surface to produce a laminate board, and forming a circuit on an outer layer of the laminate board to yield a printed wiring board; wherein said prepreg is obtained by impregnating a reinforcing material with an epoxy resin composition for a printed

wiring board and drying said composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator, and a silica filler which has a shape having at least two planes and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

11. (Canceled)

12. (Previously presented): A printed wiring board, which is formed from a laminated board; wherein said laminate board is obtained by
coupling a prepreg to a metal foil surface to produce a laminate board, and forming a circuit on an outer layer of the laminate board to yield a printed wiring board; wherein said prepreg is obtained by impregnating a reinforcing material with an epoxy resin composition for a printed wiring board and drying said composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator, and a silica filler which has a shape having at least two planes and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

13-16. (Canceled)